



JKW

PATENT
YOR920030206US1

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

In re Application of : Larry Shungwei Mok
Serial Number : 10/784,624
Filing Date : 02/23/2004
Examiner : Tho V. Duong
Group Art Unit : 3753
For : HEAT DISSIPATION
INTERFACE FOR
SEMICONDUCTOR
CHIP STRUCTURES

Sir:

In response to the Official Action dated February 25, 2008, please amend the above-identified application as follows:

In the Drawings:

Please insert the enclosed corrected drawing of Figure 5 into this Application. The page is labeled as a "Replacement Page."

In the Claims:

Please amend Claims 1 as set forth in the Appendix attached hereto.

REMARKS

The Formal Drawing of Figure 5 is enclosed. It is marked as "Replacement Page" as noted above. It contains all of the features found in the informal drawings that were filed initially with the application but adds and identifies elements 311 (upper fin members) and 314 (finger portions). No new matter/features is/are present in this drawing.